



## LTM4614 144LD 15.00mm X 15.00mm X 2.82mm (TABLE OF MATERIAL DECLARATION)

***The LTM4614 is RoHS compliant per EU RoHS Directive 2003/95/EC.***

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2295	Barium Compounds	7727-43-7	0.00344	1.500
				Filler Substances (Silica Crystalline)	-	0.09160	39.915
				Copper Metal	7440-50-8	0.12852	56.000
				Copper Compounds	1328-53-6	0.00004	0.018
				Ecotoxic substances	7439-92-1	0.00000	0.000
				Gold metal or alloy	7440-57-5	0.00106	0.460
				Nickel	7440-02-0	0.00482	2.100
				Zinc	7440-66-6	0.00002	0.007
2	Solder Paste	Alloy	0.0176	Sn	7440-31-5	0.01672	95.000
				Sb	7440-36-0	0.00088	5.000
3	Passive/Active Components		0.3176	Iron Powder (Fe)	7439-89-6	0.1436	45.210
				Copper (Cu)	7440-50-8	0.0789	24.840
				Nickel (Ni)	7440-02-0	0.0006	0.185
				Tin (Sn)	7440-31-5	0.0003	0.099
				Miscellaneous	-	0.0942	29.660
4	Active Ics	Silicon	0.0106	Silicon	7440-21-3	0.01060	100.000
5	Wire	Gold	0.0019	Au	7440-57-5	0.00194	99.990
6	Encapsulation	Epoxy Resin	1.0065	Fused Silica	60676-86-0	0.77702	77.200
				Epoxy Resin	-	0.08958	8.900
				Phenol Resin	-	0.08958	8.900
				Crytalline Silica	14808-60-7	0.03020	3.000
				Carbon Black	1333-86-4	0.00503	0.500
				Metal Hydroxide	-	0.01510	1.500
Total Package Weight			1.5837				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts